DISPLAY Elektronik GmbH

DATA SHEET

LCD MODULE

DEM 16481 SBH-PW-N

Product Specification

Version: 7.1.3

GENERAL SPECIFICATION

MODULE NO.:

DEM 16481 SBH-PW-N

CUSTOMER P/N

VERSION NO.	CHANGE DESCRIPTION	DATE
0	ORIGINAL VERSION	13.12.2002
1	ADD VERSION	15.07.2003
2	CHANGE PCB DRAWING	20.10.2003
3	ADD VERSION	04.11.2003
4	ADD VERSION	09.06.2005
5	MODIFY DESCRIPTION	19.06.2006
6	MODIFY SECTION 6.1	19.04.2007
7	MODIFY ELECTRICAL CHARACTERISTICS	17.05.2007
7.1.1	CHANGE IC	16.06.2008
7.1.2	ADD A VERSION	18.09.2014
7.1.3	Change the VDD from -0.3~+7.0 V to -0.3~+6V;VLCD from 3.0~10V to 3.0~7V in page7	08.01.2018

PREPARED BY: <u>PS</u> DATE: <u>08.01.2018</u>

APPROVED BY: MHO DATE: 08.01.2018

CONTENTS

1. FUNCTIONS & FEATURES	2
2. MECHANICAL SPECIFICATIONS	2
3. BLOCK DIAGRAM	3
4. EXTERNAL DIMENSIONS	3
5. PIN ASSIGNMENT	4
6. PCB DRAWING AND DESCRIPTION	5
7. BACKLIGHT VOLTAGE AND CURREN	6
8. DISPLAY DATA RAM	6
9. MAXIMUM ABSOLUTE POWER RATINGS	7
10. ELECTRICAL CHARACTERISTICS	7
11. CONTROL AND DISPLAY COMMAND	10
12. CHARACTR GENERATOR ROM	11
13. QUALITY DESCRIPTION	12
14. MODULES ACCEPT QUALITY LEVEL (AQL)	13
15. RELIABILITY TEST	13
16. LCD MODULES HANDLING PRECAUTIONS	14
17 OTHERS	14

1. FUNCTIONS & FEATURES

Module	LCD Type
DEM 16481 SBH-PW-N	STN BLUE Transmissive Negative Mode
Viewing Direction	: 6 O'clock
 Driving Scheme 	: 1/16 Duty Cycle, 1/5 Bias
 Power Supply Voltage 	: 5.0 Volt (typ.)
Backlight Type	: White Light guide
• VLCD Adjustable For Best Con	trast : 4.5 Volt (typ.)
 Display contents 	: 16 x 4 Characters
 Internal Memory 	: CGROM (8,320 bits)
	: CGRAM (64 x 8 bits)
	: DDRAM (80 x 8 bits)
• CGROM	: CGROM of the ST7066U-0A-B

: Easy Interface with a 4-bit or 8-bit MPU

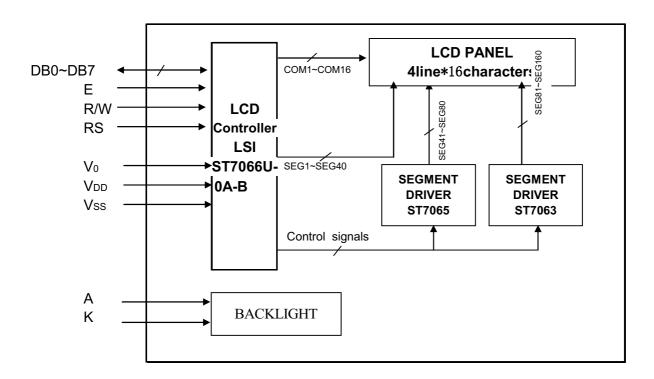
2. MECHANICAL SPECIFICATIONS

Interface

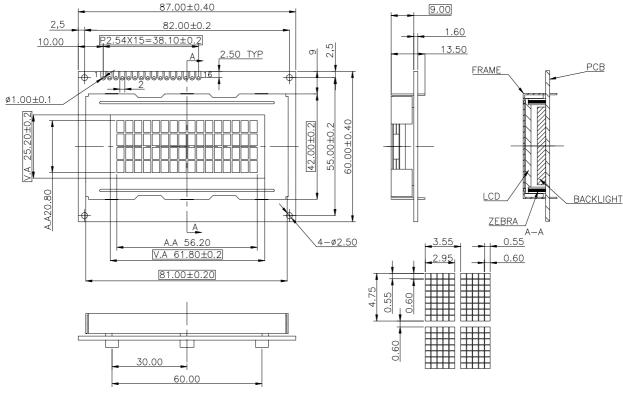
• Module Size : 87.00 x 60.00 x 13.50 mm

Character Pitch
 Character Size
 Character Font
 Dot Size
 Dot Pitch
 3.55 x 5.35 mm
 2.95 x 4.75 mm
 5 x 8 dots
 0.55 x 0.55 mm
 0.60 x 0.60 mm

3. BLOCK DIAGRAM



4. EXTERNAL DIMENSIONS



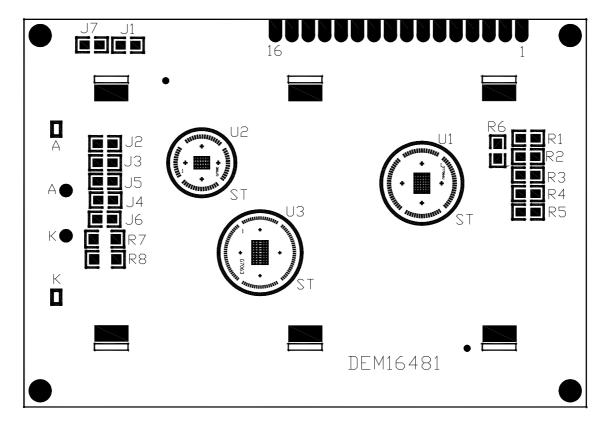
REMARKS:

1.UNMARKED TOLERANCE IS ±0.5 2.ALL MATERIAL COMPLY WITH ROHS

5. PIN ASSIGNMENT

Pin No.	Symbol	Function
1	VSS	Ground terminal of module.
2	VDD	Power terminal of module 5.0V.
3	V0	Power Supply for liquid crystal drive.
4	RS	Register select RS = 0···Instruction register RS = 1···Data register
5	R/W	Read /Write R/W = 1···Read R/W = 0···Write
6	Е	Read/Write Enable Signal
7	DB0	
8	DB1	
9	DB2	Bi-directional data bus, data transfer is performed once, thru DB0 to DB7, in
10	DB3	the case of interface data. Length is 8-bits; and twice, thru DB4 to DB7, in
11	DB4	case of interface data length is 4-bits. Upper four bits first then lower four
12	DB5	bits.
13	DB6	
14	DB7	
15	LED – (K)	Please also refer to 6.1 PCB drawing and description.
16	LED + (A)	Please also refer to 6.1 PCB drawing and description.

6. PCB DRAWING AND DESCRIPTION



Note: The part no. DEM16481 is printed on the PCB.

DESCRIPTION:

6-1-1. The polarity of the pin 15 and the pin 16

LED Polarity(1)								
15 Pin 16Pin								
Anode	Cathode							
J3=J5=open								
J2 = J4 =	J2=J4=closed							

LED Polarity(2)								
15 Pin	16 Pin							
Cathode	Anode							
J3 = J5 = closed								
J2=J4=	J2=J4= open							

Note: In application module, J2=J4= open and J3=J5=0 Ohm

6-1-2. The metal-bezel is set be on ground when the J1 is solder-Bridge.

Note: In application module, J1=0 Ohm

6-1-3. The LED resistor should can be bridged when the J6 is solder-Bridge.

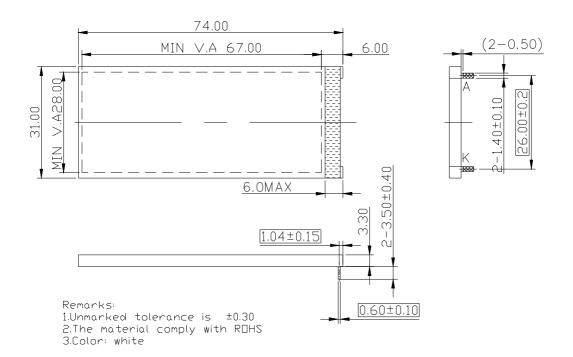
Note: In application module, J6=open

6-1-4. The R7 and the R8 are the LED resistor.

Note: In application module, R7=15 Ohm, R8=open

7. BACKLIGHT VOLTAGE AND CURREN

	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS	
Forward Voltage	Vf		4.0	4.2	V	If= 80mA	
Forward Current	l f		80	100	mA		
Power Dissipation	Pd		0.32		W	If= 80mA	
Reverse Voltage	٧R		4.0		V		
Reverse Current	IR		1.2		mA		
Luminous Intensity	IV		110.0		cd/m ²	If= 80mA	
Luminous Uniformity		70			%	II- OUIIIA	
Emitted Color	Ec				K		
Emission Wavelength	λР		White		nm	If =20mA Ta=25;	
Spectral Range	Δλ		20		nm	Each chip	



8. DISPLAY DATA RAM (DDRAM)

		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Display position
FIRST	LINE	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	OD	0E	OF.	DDRAM Address
SECOND	LINE	40	41	42	43	44	45	46	47	48	49	4A	4 B	4C	4 D	4E	4F	
THIRD	LINE	10	11	12	13	14	15	16	17	18	19	1A	1B	1C	1 D	1E	1F	
FOURTH	LINE	50	51	52	53	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	

9. MAXIMUM ABSOLUTE LIMIT

Item	Symbol	Standard value	Unit
Power supply voltage(1)	V_{DD}	-0.3~+6.0	V
Power supply voltage(2)	V_{LCD}	V _{DD} -10.0~V _{DD} +0.3	V
Input voltage	$V_{ m IN}$	-0.3~V _{DD} +0.3	V
Operating temperature	Topr	-20~+70	°C
Storage temperature	Tstg	-30~+80	°C

^{*}Voltage greater than above may damage to the Circuit.

VDD>V1>V2>V3>V4>V5

10. ELECTRICAL CHARACTERISTICS

10-1 DC Characteristics

10-1-1 DC Characteristics(VDD=4.5V~5.5V,Ta=-20~+70°C)

Itom	Crembal	St	andard Val	ue	Test	Unit	
Item	Symbol	MIN	TYP	MAX	Condition	Oilit	
Operating Voltage	$V_{ m DD}$	4.5	5.0	5.5		V	
	Iddi		0.7	1.0	Ceramic oscillation fosc=250kHz		
Supply Current	I _{DD2}		0.4	0.6	Resistor oscillation external clock operation fosc=270kHz	mA	
LCD Driving Voltage	VLCD	3.0	4.5	7.0	V _{DD} -V ₅ (1/5,1/4 Bias)	V	

(CONTINUED) (VDD=2.7V~4.5V,Ta=-20~+70°C)

Item	Cumbal	St	andard Val	ue	Test	Unit	
Item	Symbol	MIN	TYP	MAX	Condition	Omi	
Operating Voltage	$V_{ m DD}$	2.7		4.5		V	
	\mathbf{I}_{DD1}		0.3	0.5	Ceramic oscillation fosc=250kHz		
Supply Current	urrent I _{DD2}		0.17	0.3	Resistor oscillation external clock operation fosc=270kHz	mA	
LCD Driving Voltage	VLCD	3.0		7.0	V _{DD} -V ₅ (1/5,1/4 Bias)	V	

10-2 AC Characteristics

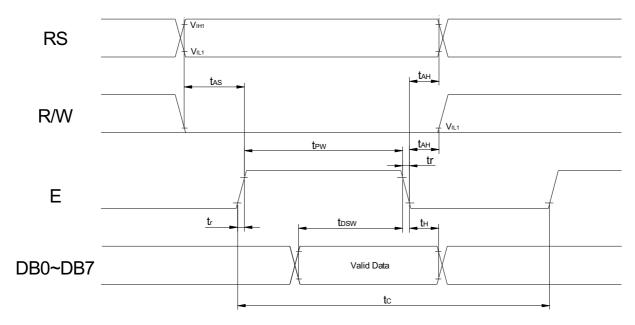
10-2-1 Write mode (writing data from MPU to module)

Item	Symbol	Min	Тур	Max	Unit	Test PIN
E Cycle Time	t _C	1200			ns -	E
E Rise/Fall Time	t _R ,t _F			25	ns	Е
E Pulse Width (High, Low)	t _w	140			ns	E
R/W and RS Setup Time	t _{su1}	0			-ns	R/W,RS,E
R/W and RS Hold Time	t _{H1}	10			ns	R/W,RS,E
Data Setup Time	t _{su2}	40			ns	DB0~DB7
Data Hold Time	t _{H2}	10			ns	DB0~DB7

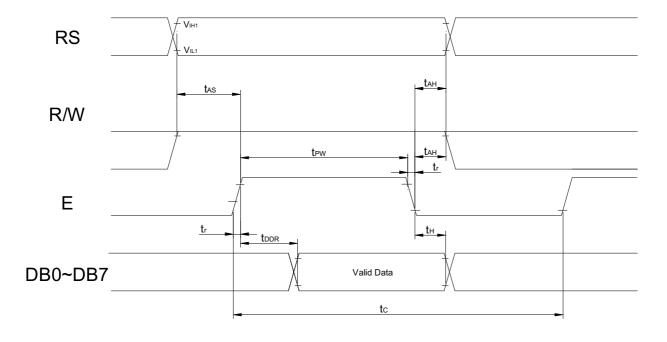
10-2-2 Read Mode (Reading Data from module to MPU)

Characteristic	Symbol	Min	Type	Max	Unit	Test PIN
E Cycle Time	$t_{\rm C}$	1200			ns	Е
E Rise Time	t_{R}			25	ns	Е
E Fall Time	t_{F}			25	ns	Е
E Pulse width	tp _W	140			ns	Е
Address Setup Time	$t_{ m AS}$	0			ns	R/W,RS,E
Address Hold Time	t_{AH}	10			ns	R/W,RS,E
Data Setup Time	$t_{ m DDR}$			100	ns	DB0~DB7
Data Hold Time	t _H	10			ns	DB0~DB7

10-3-1 Write mode



10-3-2 Read mode



11. CONTROL AND DISPLAY COMMAND

Command	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Execution time (fosc=270KHz)	Remark
Clear Display	0	0	0	0	0	0	0	0	0	1	1.52ms	Write"20H" to DDRAM. And set DDRAM address to "00H" from AC
Return home	0	0	0	0	0	0	0	0	1	х	1.52ms	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.
Entry mode Set	0	0	0	0	0	0	0	1	I/D	S	37us	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.
Display on/off control	0	0	0	0	0	0	1	D	С	В	37us	D=1: entire display on C=1: cursor on B=1: cursor position on
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	X	X	37us	Set cursor moving and display shift control bit, and the direction, without changing DDRAM data.
function Set	0	0	0	0	1	DL	N	F	X	X	37us	DL: interface data is 8/4 bits N: number of line is 2/1 F: font size is 5x11/5x8
Set CGRAM address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	37us	Set CGRAM address in address counter
Set DDRAM address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	37us	Set DDRAM address in address counter
Read busy flag& address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	0us	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.
Write data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	37us	Write data into internal RAM (DDRAM/CGRAM)
Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	37us	Read data from internal RAM (DDRAM / CGRAM)

Note:

Be sure the ST7066U is not in the busy state (BF=00 before sending an instruction from the MPU to the ST7066U. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself. Refer to instruction table for the list of each instruction execution time.

12. CHARACTER GENERATOR ROM (ST7066U-0A-B)

U ppea(48it)	0 0 0 0	0 0 0 1	0010	0011	0100	0101	0110	0111	1000	1001	10010	1011	1100	1101	1110	1111
0 0 0 0 0	CGRAM (1)															
0 0 0 1	(2)															
0010	(3)															
0 0 1 1	(4)															
0100	(5)															
0 1 0 1	(6)															
0110	(7)															
0111	(8)															
1000	(1)															
1001	(2)															
1010	(3)															
1011	(4)															
1100	(5)															
1101	(6)															
1110	(7)															
1111	(8)															

13. QUALITY DESCRIPTION

DEFECT SPECIFICATION:

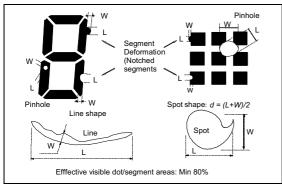
Specific type-related items are covered in this sheet.

a: Table for Cosmetic defects

(Note: nc = not counted).

Sizes and number of defects

(Max. Qty)



Examples/

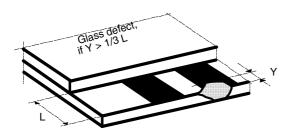
Shapes

b: Glass defects

b1:Glass defects at contact ledge

Defect Type	Max. defect size [μm] d or L W	Max. Quantity.
Black or White Spots	d ≤ 100	nc
	100 < d ≤ 200	5
Black or White Lines	 W ≤ 10	nc
	L ≤ 5000 W ≤ 30	3
	L ≤ 2000 W ≤ 50	2
Pinhole	$d \le 100$ $100 < d \le 200$	nc 1/segme nt
(Total	defects)	(5)
Segment Deformation	W ≤ 100	nc
Bubble (e.g. under pola)	d ≤ 150	nc
	200 < d ≤ 400	3
	400 < d ≤ 600	1

b2:Glass chipping in other areas shall not be in conflict



with the product's function.

14. MODULE ACCEPT QUALITY LEVEL (AQL)

14.1 AQL Standard Value: Fatal Defect = 0.1, Major Defect = 0.65; Minor Defect = 2.5.

14.2 Curtailed Inspection Scheme

Type	Batch Qty	inspection Qty	AQL value	pass	Reject
	350PCS<	125pcs	0.1	0	1
	1000PCS		0.65	2	3
			2.5	7	8
	200PCS<	80pcs	0.1	0	1
module	350PCS		0.65	1	2
product			2.5	5	6
	<200PCS	32pcs	0.1	0	1
			0.65	0	1
			2.5	4	5
Module	<200PCS	All	/	/	The sample will be reject when
sample		inspected			the fateful defect > 2pcs or main
	>200PCS	125pcs			defect > 5pcs.

Notes: 1). Batch QTY is the production amount that Production department ship to QA department.

2). All of product will be inspected if the batch QTY less than inspected QTY.

3). Each batch fixed to be 500pcs.

15. RELIABILITY TEST

Operating life time: Longer than 50000 hours (at room temperature without direct irradiation of sunlight) Reliability characteristics shall meet following requirements.

TEMPERATURE TESTS	NORMAL GRADE
High temperature storage	+80°C x 96hrs
	(Without Polarizer)
Low temperature storage	-30°C x 96hrs
High temperature operation	+70°C x 96hrs
Low temperature operation	-20°C x 96hrs
High temperature, High humidity	+70°C x 95%RH x 96hrs
	(Without Polarizer)
Thermal shock	-20°C x 30min. ← 10s
Vibration test	Frequency x Swing x Time 40Hz x 4mm x 4hrs
Drop test	Drop height x Times 1.0m x 6times

16. LCD MODULES HANDLING PRECAUTIONS

- Please remove the protection foil of polarizer before using.
- The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- If the display panel is damaged and the liquid crystal substance inside it leaks out, do not get any in your mouth. If the substance come into contact with your skin or clothes promptly wash it off using soap and water.
- Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarize carefully.
- To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - -Be sure to ground the body when handling the LCD module.
 - -Tools required for assembly, such as soldering irons, must be properly grounded.
 - -To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
 - -The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.

Storage precautions

When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps. Keep the modules in bags designed to prevent static electricity charging under low temperature / normal humidity conditions (avoid high temperature / high humidity and low temperatures below 0°C). Whenever possible, the LCD modules should be stored in the same conditions in which they were shipped from our company.

17. OTHERS

- Liquid crystals solidify at low temperature (below the storage temperature range) leading to defective orientation of liquid crystal or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subjected to a strong shock at a low temperature.
- If the LCD modules have been operating for a long time showing the same display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. Abnormal operating status can be resumed to be normal condition by suspending use for some time. It should be noted that this phenomena does not adversely affect performance reliability.
- To minimize the performance degradation of the LCD modules resulting from caused by static electricity, etc. exercise care to avoid holding the following sections when handling the modules:
 - Exposed area of the printed circuit board
 - Terminal electrode sections